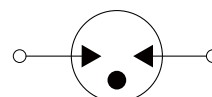


FEATURES

- | Surface Mounting Design 5.5*5.5*6.0mm
- | High Current Handling Capability 10,000A @ 8/20 μ s
- | Low Capacitance and Insertion Loss
- | Quick Response and Long Service Life
- | Moisture sensitivity level: Level 1
- | High Reliability and Automobile Grade(AEC-Q200)



5.5*5.5*6.0mm




Schematic Symbol

APPLICATION INFORMATION

- | Communication equipment.
- | Repeaters, Modems
- | Telephone Interface, Line cards.
- | Data communication equipment.

AGENCY APPROVALS

Icon	Solderability
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003
	Mean lead free

PRODUCT CHARACTERISTICS

Lead Material	Body Material	Terminal Finish
Copper or Fe-Ni alloy	Ceramics	100% Matte-Tin Plated

ELECTRICAL PARAMETER

Parameter	Symbol	Limit	Unit
DC Blocking Voltage 1)	100V/s	72-108	V
Impulse Spark-over Voltage	At 1kV/ μ s	for 99 % of measured values \leq 900	V
	At 1kV/ μ s	Typical values of distribution \leq 850	V
Impulse Discharge Current 2)	8/20 μ s	10,000	A
Insulation Resistance	DC=50V	\geq 1	G Ω
Capacitance at 1MHz	V _{DC} =0.5V	\leq 1.5	pF
Operating And Storage Temperature		-40-125	°C

1) In ionized mode

2) Terms and waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-21

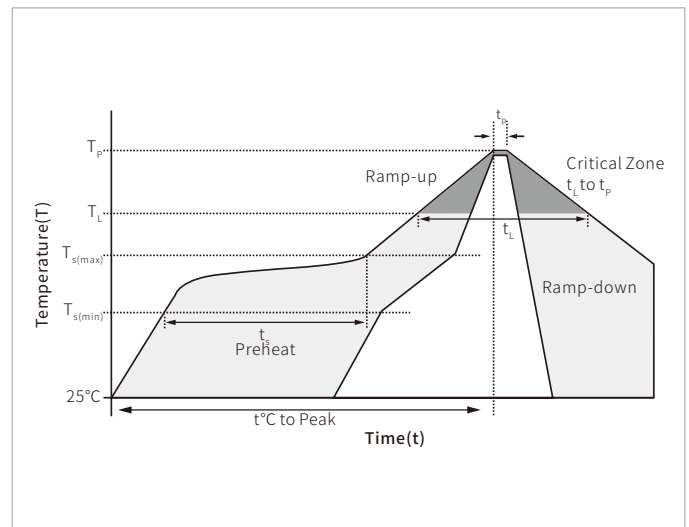
ENVIRONMENTAL RELIABILITY CHARACTERISTICS

Testing items	Technical standards
High Temperature Storage Test	Temperature: 85°C ; Time:2H
Low Temperature Storage Test	Temperature: -40°C ; Time:2H
Vibration	Frequency: 10-500Hz ; Amplitude:0.15mm ; Time:45min
Resistance of soldering heat	Temperature: 260 \pm 5°C; Time of dip soldering: 10s, 1time

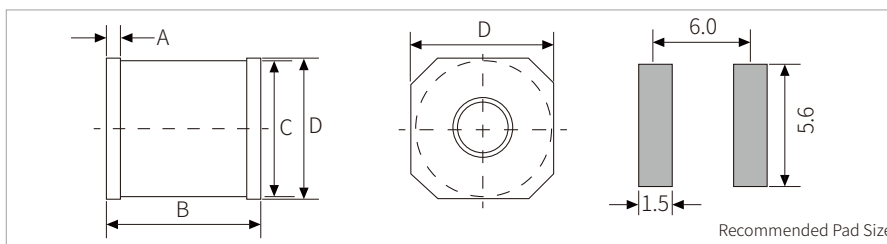
NOTE: Up-screen program can be specified by customer' s request via contacting Semiware service

REFLOW PROFILE

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Min	150°C
	Temperature Max	200°C
	Time(min to max)	60 – 180 secs
Average ramp up rate (Liquidus)Temp (T_L) to peak $T_s(max)$ to T_L - Ramp-up Rate		3°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time(min to max)(t_s)	60 – 150 seconds
Peak Temperature (T_p)		260 °C
Time within 5°C of actual peak Temperature (t_p)		10-30 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C



DIMENSIONS AND RECOMMENDED SOLDERING PAD



Ref.	Outline Dimensions
	Millimeters
A	0.5±0.2
B	6.0±0.2
C	5.4±0.2
D	5.5±0.2

ORDERING INFORMATION

Part Number	Size	Marking	QTY/Reel	Reel Size
TPSG2R05B090C	5.5*5.5*6.0mm	 SG090 05	1000PCS	13"

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By QR Code

Website



Wechat

To find your local partner within Semiware's global website: www.semiware.com

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